



Material Content Data Sheet



Sales Product Name				IPD031N06L3 G		Issued		20. July 2018	
MA#				MA000505426					
Package				PG-TO252-3-11		Weight*		377.50 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	5.184	1.37	1.37	13732	13732	
leadframe	non noble metal	iron	7439-89-6	0.215	0.06		570		
	inorganic material	phosphorus	7723-14-0	0.065	0.02		171		
	non noble metal	copper	7440-50-8	215.017	56.96	57.04	569578	570319	
wire	non noble metal	aluminium	7429-90-5	47.697	12.63	12.63	126349	126349	
encapsulation	organic material	carbon black	1333-86-4	0.823	0.22		2179		
	plastics	epoxy resin	-	14.397	3.81		38138		
	inorganic material	silicondioxide	60676-86-0	67.050	17.76	21.79	177616	217933	
leadfinish	non noble metal	tin	7440-31-5	3.787	1.00	1.00	10031	10031	
plating	non noble metal	nickel	7440-02-0	0.091	0.02		240		
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.02	1	241	
solder	noble metal	silver	7440-22-4	0.099	0.03		263		
	non noble metal	tin	7440-31-5	0.079	0.02		211		
	non noble metal	lead	7439-92-1	3.796	1.01	1.06	10054	10528	
heatspreader	non noble metal	iron	7439-89-6	0.019	0.01		51		
	inorganic material	phosphorus	7723-14-0	0.006	0.00		15		
	non noble metal	copper	7440-50-8	19.177	5.08	5.09	50801	50867	
*deviation	< 10%		Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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